

L Number	Hits	Search Text	DB	Time stamp
1	61276	451/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:18
2	270052	451/\$.ccls. and wafers or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:27
3	3034	451/\$.ccls. and slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:20
4	425674	451/\$.ccls. and cleaning or clean	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:26
5	229202	451/\$.ccls. and spray or spraying	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:26
6	2185	(451/\$.ccls. and wafers or wafer) and (451/\$.ccls. and slurry)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:22
7	25109	(451/\$.ccls. and cleaning or clean) and (451/\$.ccls. and spray or spraying)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:23
8	246	((451/\$.ccls. and wafers or wafer) and (451/\$.ccls. and slurry)) and ((451/\$.ccls. and cleaning or clean) and (451/\$.ccls. and spray or spraying))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:23
9	0	((((451/\$.ccls. and wafers or wafer) and (451/\$.ccls. and slurry)) and ((451/\$.ccls. and cleaning or clean) and (451/\$.ccls. and spray or spraying)))) and (wafer or wafers) same (slurry) same (cleaning or clean) same (spray or spraying)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:26
10	4714	451/\$.ccls. and (cleaning or clean)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:26
11	1757	451/\$.ccls. and (spray or spraying)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:26
12	3778	451/\$.ccls. and (wafers or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:27

13	1247	(451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:27
14	518	(451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:28
15	246	((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:28
16	140	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:29
17	3	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and (first adj3 speed) and (second adj3 speed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:41
18	0	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and (first same speed) and (second same speed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:42
19	0	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and (first) and (second)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:44
20	129	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and first	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:44
21	122	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:44
22	85	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and speed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:45
23	76	(((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and first) and (((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and second) and (((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and speed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:46

24	30	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and first) and (((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and second) and (((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and speed)) and "first" same "speed"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:47
25	26	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and first) and (((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and second) and (((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and speed)) and "second" same "speed"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:48
26	20	((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and first) and (((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and second) and (((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and speed)) and "first" same "speed") and (((((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and first) and (((((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and second) and (((((((451/\$.ccls. and slurry) and (451/\$.ccls. and (cleaning or clean))) and ((451/\$.ccls. and (spray or spraying)) and (451/\$.ccls. and (wafers or wafer)))) and (spray or spraying) same (cleaning or clean)) and speed)) and "second" same "speed")) and "second" same "speed"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 01:48

L Number	Hits	Search Text	DB	Time stamp
1	34073	134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:02
2	3548	134/\$.ccls. and (wafer or wafers)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:02
3	991	134/\$.ccls. and slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:02
4	14657	134/\$.ccls. and (cleaning or clean)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:03
5	7016	134/\$.ccls. and (spray or spraying)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:03
6	126	(134/\$.ccls. and (wafer or wafers)) and (134/\$.ccls. and slurry) and (134/\$.ccls. and (cleaning or clean)) and (134/\$.ccls. and (spray or spraying))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:04
7	26	((134/\$.ccls. and (wafer or wafers)) and (134/\$.ccls. and slurry) and (134/\$.ccls. and (cleaning or clean)) and (134/\$.ccls. and (spray or spraying))) and (wafer or wafers) same (slurry) same (cleaning or clean) same (spray or spraying)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:06
8	0	((134/\$.ccls. and (wafer or wafers)) and (134/\$.ccls. and slurry) and (134/\$.ccls. and (cleaning or clean)) and (134/\$.ccls. and (spray or spraying))) and (wafer or wafers) same (slurry) same (cleaning or clean) same (spray or spraying)) and (first adj3 speed) and (second adj3 speed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:08
9	4	((134/\$.ccls. and (wafer or wafers)) and (134/\$.ccls. and slurry) and (134/\$.ccls. and (cleaning or clean)) and (134/\$.ccls. and (spray or spraying))) and (wafer or wafers) same (slurry) same (cleaning or clean) same (spray or spraying)) and (first) and (second) and (speed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/26 14:08